

### 论文摘要

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## 急冷条件下Cu-Sn合金的快速枝晶生长

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**摘要:** 研究快速凝固Cu-xSn( $x=7\%$ , 13.5%, 质量分数)合金的相结构、组织形态和枝晶生长特性, 将金属熔体热传导方程与Navier-Stokes方程相耦合, 从理论上计算液态合金的冷却速率。结果表明: 在急冷快速凝固条件下, Cu-7%Sn合金形成过饱和的单相 $\alpha$ -Cu固溶体组织; Cu-13.5%Sn合金形成以亚稳的Cu<sub>13.7</sub>Sn相为主相、 $\alpha$ -Cu为第二相的快速凝固组织; 随着冷却速率的增大, 溶质截留效应增强, 合金相结构由复相向单相转变; 沿垂直于辊面方向上合金的组织形态依次为近辊面细小等轴晶、中部柱状晶及自由面粗大等轴晶; 增大冷却速率, 晶体形态由柱状晶向等轴晶转变; 在急冷快速凝固过程中,  $\alpha$ -Cu和Cu<sub>13.7</sub>Sn相均以枝晶方式生长; 随温度梯度的增大, 晶体生长速率呈线性增大。

**关键字:** Cu-Sn合金; 单辊法; 急冷快速凝固; 晶体生长

## Rapid dendritic growth in melt-spun Cu-Sn alloys

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**Abstract:** The phase structure and microstructural characteristics of rapidly solidified Cu-xSn( $x=7\%$ , 13.5%, mass fraction) alloys were investigated. The cooling rate was calculated theoretically by coupling the heat conduct equation and Navier-Stokes equation. The results show that under rapid solidification condition, the single phase  $\alpha$ -Cu solid solution is formed in Cu-7%Sn alloy. The microstructure of Cu-13.5%Sn alloy consists of main phase Cu<sub>13.7</sub>Sn and a few of  $\alpha$ -Cu phase. With increasing cooling rate, the effect of solute trapping is enhanced, and the phase structure changes from multiphase to single-phase. The microstructures of the alloy along the direction vertical to wheel surface are characterized by fine equiaxed, columnar and coarse equiaxed grain, respectively. Both  $\alpha$ -Cu and Cu<sub>13.7</sub>Sn phase grow in the manner of dendritic growth. With increasing temperature gradient, the growth rate of columnar crystals increases linearly.

**Key words:** Cu-Sn alloy; melt-spun method; rapid solidification; crystal growth

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